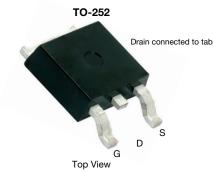


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# N-Channel 100 V (D-S) MOSFET

| PRODUCT SUMMARY     |                                   |                                   |        |  |  |  |
|---------------------|-----------------------------------|-----------------------------------|--------|--|--|--|
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω) MAX.      | $R_{DS(on)}$ (Ω) MAX. $I_D$ (A) ° |        |  |  |  |
| 100                 | 0.0089 at V <sub>GS</sub> = 10 V  | 50                                | 33 nC  |  |  |  |
| 100                 | 0.0093 at V <sub>GS</sub> = 7.5 V | 50                                | 33 110 |  |  |  |



### **Ordering Information:**

SUD70090E-GE3 (lead (Pb)-free and halogen-free)

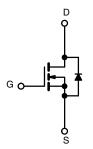
#### **FEATURES**

- ThunderFET® power MOSFET
- Maximum 175 °C junction temperature
- Q<sub>gd</sub> / Q<sub>gs</sub> ratio < 1 optimizes switching characteristics
- 100 % R<sub>g</sub> and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

### **APPLICATIONS**

- DC/DC converter
- Power tools
- · Motor drive switch
- DC/AC inverter
- Battery management





N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted) |                          |                                   |             |      |  |  |
|---|--------------------------|-----------------------------------|-------------|------|--|--|
| PARAMETER   |                          | SYMBOL                            | LIMIT       | UNIT |  |  |
| Drain-Source Voltage  | V <sub>DS</sub>          | 100                               | V           |      |  |  |
| Gate-Source Voltage   | V <sub>GS</sub>          | ± 20                              | V           |      |  |  |
| Continuous Dusis Courset (T., 150 °C)                                     | T <sub>C</sub> = 25 °C   | ,                                 | 50 °        |      |  |  |
| Continuous Drain Current (T <sub>J</sub> = 150 °C)                        | T <sub>C</sub> = 70 °C   | I <sub>D</sub>                    | 50 °        |      |  |  |
| sed Drain Current (t = 100 µs)  |                          | I <sub>DM</sub>                   | 120         | А    |  |  |
| Avalanche Current   |                          | I <sub>AS</sub>                   | 40          |      |  |  |
| Single Avalanche Energy <sup>a</sup>                                      | L = 0.1 mH               | E <sub>AS</sub>                   | 80          | mJ   |  |  |
| Marrian Danier Disable atting 8   | T <sub>C</sub> = 25 °C   | Б                                 | 125         | W    |  |  |
| Maximum Power Dissipation <sup>a</sup>                                    | T <sub>C</sub> = 70 °C b | P <sub>D</sub>                    | 87.5        |      |  |  |
| Operating Junction and Storage Temperature R                              | ange                     | T <sub>J</sub> , T <sub>stg</sub> | -55 to +175 | °C   |  |  |

| THERMAL RESISTANCE RATINGS                   |                   |       |      |  |  |  |
|--|-------------------|-------|------|--|--|--|
| PARAMETER                                    | SYMBOL            | LIMIT | UNIT |  |  |  |
| Junction-to-Ambient (PCB Mount) <sup>b</sup> | R <sub>thJA</sub> | 40    | °C/W |  |  |  |
| Junction-to-Case (Drain)                     | R <sub>thJC</sub> | 1.2   |      |  |  |  |

#### Notes

- a. Duty cycle ≤ 1 %.
- b. When mounted on 1" square PCB (FR4 material).
- c. Package limited.



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| PARAMETER                                     | SYMBOL               | TEST CONDITIONS   | MIN. | TYP.   | MAX.   | UNIT |  |
|---|----------------------|---|------|--------|--------|------|--|
| Static  |                      |   |      |        |        |      |  |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>      | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$                           | 100  | -      | -      | V    |  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub>  | $V_{DS}=V_{GS},I_D=250\;\mu A$  | 2    | -      | 4      |      |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>     | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$                       | -    | -      | ± 250  | nA   |  |
|   |                      | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V                          | -    | -      | 1      | μА   |  |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>     | $V_{DS}$ = 100 V, $V_{GS}$ = 0 V, $T_J$ = 125 °C                        | -    | -      | 150    |      |  |
|   |                      | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C | -    | -      | 5      | mA   |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>   | $V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$                        | 50   | -      | -      | Α    |  |
| Duain Caluma On State Resistance 2            | Б                    | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A                           | -    | 0.0074 | 0.0089 | Ω    |  |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub>  | V <sub>GS</sub> = 7.5 V, I <sub>D</sub> = 15 A                          | -    | 0.0077 | 0.0093 |      |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>      | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A                           | -    | 38     | -      | S    |  |
| Dynamic <sup>b</sup>                          |                      |   |      |        |        |      |  |
| Input Capacitance                             | C <sub>iss</sub>     | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 50 V, f = 1 MHz                | -    | 1950   | -      | pF   |  |
| Output Capacitance                            | C <sub>oss</sub>     |   | -    | 845    | -      |      |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>     |   | -    | 54     | -      |      |  |
| Total Gate Charge <sup>c</sup>                | Qg                   |   | -    | 33     | 50     | nC   |  |
| Gate-Source Charge <sup>c</sup>               | Q <sub>gs</sub>      | $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$      | -    | 8.8    | -      |      |  |
| Gate-Drain Charge <sup>c</sup>                | Q <sub>gd</sub>      |   | -    | 7.5    | -      |      |  |
| Gate Resistance                               | $R_g$                | f = 1 MHz   | 0.7  | 3.5    | 7      | Ω    |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>   |   | -    | 15     | 30     |      |  |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>       | $V_{DD} = 50 \text{ V}, R_L = 5 \Omega$                                 | -    | 27     | 54     | ns   |  |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>  | $I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$        | -    | 36     | 72     |      |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>       |   | -    | 45     | 90     |      |  |
| Drain-Source Body Diode Ratings ar            | nd Characteris       | stics <sup>b</sup> (T <sub>C</sub> = 25 °C)                             |      |        |        |      |  |
| Pulsed Current (t = 100 μs)                   | I <sub>SM</sub>      |   | -    | -      | 120    | Α    |  |
| Forward Voltage <sup>a</sup>                  | V <sub>SD</sub>      | I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V                            | -    | 0.8    | 1.5    | V    |  |
| Reverse Recovery Time                         | t <sub>rr</sub>      |   | -    | 77     | 116    | ns   |  |
| Peak Reverse Recovery Charge                  | I <sub>RM(REC)</sub> | $I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$        | -    | 4.2    | 6.3    | Α    |  |
| Reverse Recovery Charge                       | Q <sub>rr</sub>      | •   | -    | 145    | 365    | nC   |  |

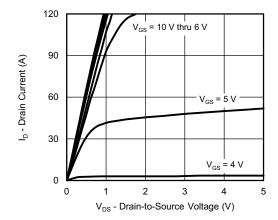
#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

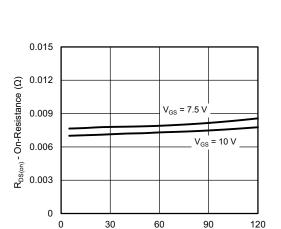
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

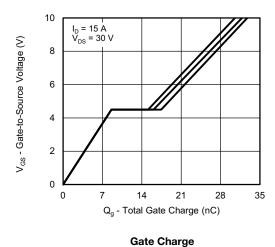


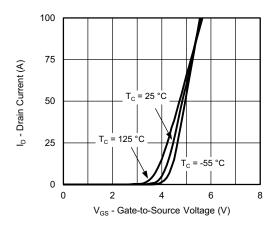
### **Output Characteristics**



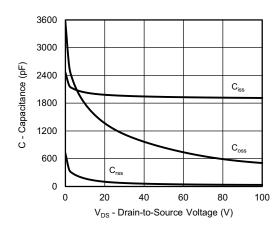
On-Resistance vs. Drain Current

I<sub>D</sub> - Drain Current (A)

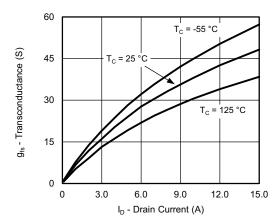




**Transfer Characteristics** 



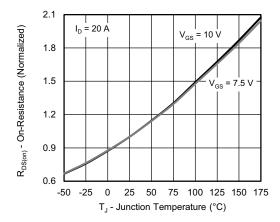
Capacitance



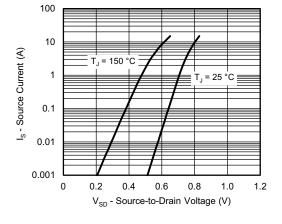
Transconductance



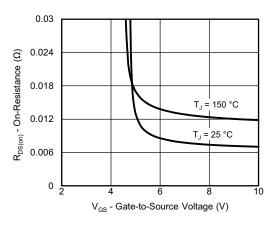
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



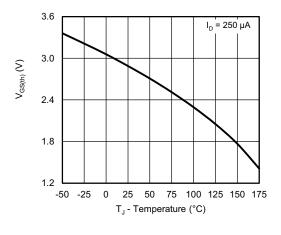
On-Resistance vs. Junction Temperature



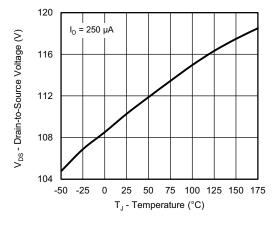
**Source Drain Diode Forward Voltage** 



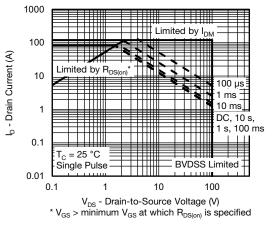
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



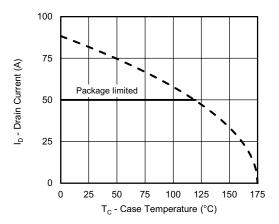
**Drain Source Voltage vs. Junction Temperature** 



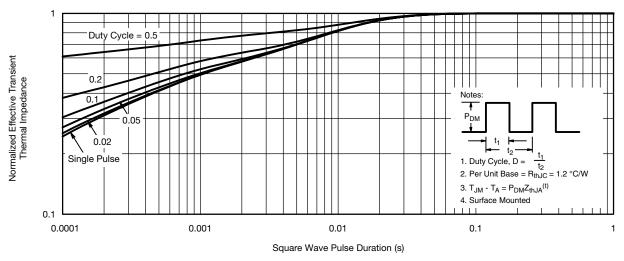
Safe Operating Area



## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



### **Current De-Rating**



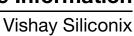
Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- · The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction to Case (25 °C)

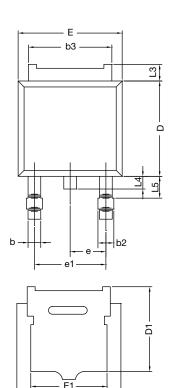
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

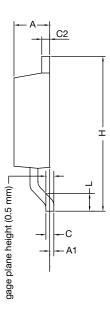
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## **TO-252AA Case Outline**





|                                 | MILLIMETERS |          | INCHES    |           |  |  |
|---------------------------------|-------------|----------|-----------|-----------|--|--|
| DIM.                            | MIN.        | MAX.     | MIN.      | MAX.      |  |  |
| Α                               | 2.18        | 2.38     | 0.086     | 0.094     |  |  |
| A1                              | -           | 0.127    | -         | 0.005     |  |  |
| b                               | 0.64        | 0.88     | 0.025     | 0.035     |  |  |
| b2                              | 0.76        | 1.14     | 0.030     | 0.045     |  |  |
| b3                              | 4.95        | 5.46     | 0.195     | 0.215     |  |  |
| С                               | 0.46        | 0.61     | 0.018     | 0.024     |  |  |
| C2                              | 0.46        | 0.89     | 0.018     | 0.035     |  |  |
| D                               | 5.97        | 6.22     | 0.235     | 0.245     |  |  |
| D1                              | 4.10        | -        | 0.161     | -         |  |  |
| Е                               | 6.35        | 6.73     | 0.250     | 0.265     |  |  |
| E1                              | 4.32        | -        | 0.170     | -         |  |  |
| Н                               | 9.40        | 10.41    | 0.370     | 0.410     |  |  |
| е                               | 2.28 BSC    |          | 0.090 BSC |           |  |  |
| e1                              | 4.56        | 4.56 BSC |           | 0.180 BSC |  |  |
| L                               | 1.40        | 1.78     | 0.055     | 0.070     |  |  |
| L3                              | 0.89        | 1.27     | 0.035     | 0.050     |  |  |
| L4                              | -           | 1.02     | -         | 0.040     |  |  |
| L5                              | 1.01        | 1.52     | 0.040     | 0.060     |  |  |
| ECN: T16-0236-Rev. P, 16-May-16 |             |          |           |           |  |  |

ECN: T16-0236-Rev. P, 16-May-16 DWG: 5347

## Notes

• Dimension L3 is for reference only.



## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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